

ABSTRACT OF THE DISCLOSURE

An integrated circuit package having a die pad with a first face and a second face, a plurality of inner leads, and a plurality of sides between the first face and the second face. The plurality of inner leads is disposed substantially co-planer with and substantially around the die pad. The package also comprises a plurality of outer leads disposed substantially co-planar with and substantially around the plurality of inner leads and the die pad, so that the sides of each of the plurality of outer leads are offset from the sides of each of the plurality of inner leads. A first adhesive layer disposed on the first face of the die pad and a second adhesive layer disposed on the first faces of each of the plurality of inner leads. An IC chip is coupled to the first face of the die pad through the first adhesive layer and to the plurality of inner leads through the second adhesive layer. The package further comprises wires linking the inner leads and outer leads to the IC chip.